

October 14th, 2025

DECLARATION OF SUBSTANCES FOR A TYPICAL GLOBALFOUNDRIES PRODUCT 200mm (8 INCH) AND 300mm (12 INCH) WAFER BASIS IN DIE FORM

The following substances are generally present in the final wafer deliverables built at GlobalFoundries (GF) fabs worldwide.

(OT) Tabs Worldwide.				
ELEMENT OR CHEMICAL	CAS NUMBER	CONTENT (PPM)	USE	
SILICON (Si)	7440-21-3	>970000	SUBSTRATE	
COPPER (Cu)	7440-50-8	<10000	CIRCUITRY	
SILICON DIOXIDE (SiO ₂)	7631-86-9	<5000	INSULATING LAYER	
ALUMINUM (AI)	7429-90-5	<2500	CIRCUITRY	
SILICON NITRIDE (Si ₃ N ₄)	12033-89-5	<1200	INSULATING LAYER	
TANTALUM (Ta)	7440-25-7	<1000	CIRCUITRY	
NICKEL (Ni)	7440-02-0	<30	CIRCUITRY	
TUNGSTEN (W)	7440-33-7	<30	CIRCUITRY	
TITANIUM (Ti)	7440-32-6	<20	BARRIER	
TITANIUM NITRIDE (TIN)	25583-20-4	<20	BARRIER	
TANTALUM NITRIDE (TaN)	12033-62-4	<20	BARRIER	
COBALT(Co)	7440-48-4	<5	CIRCUITRY	

The following substances may also be present in some GlobalFoundries wafer deliverables.

ELEMENT OR CHEMICAL	CAS NUMBER	CONTENT (PPM)	USE
BORON (B)	7440-42-8	<1	DOPANT
INDIUM (In)	7440-74-6	<1	DOPANT
ANTIMONY (Sb)	7440-36-0	<1	DOPANT
ARSENIC (As)	7440-38-2	<1	DOPANT
PHOSPHORUS (P)	7723-14-0	<1	DOPANT
GERMANIUM (Ge)	7440-56-4	<1	DOPANT
CARBON (C)	7440-44-0	<1	DOPANT
MAGNESIUM(Mg)	7439-95-4	<1	DOPANT
MANGANESE (Mn)	7439-96-5	<1	DOPANT

The data represented in the tables above are based on an average 200mm wafer weighing 53 grams and an average 300mm wafer weighing 135 grams. For this summary, the silicon wafer thickness is assumed to be 725 μ m for 200mm wafer and 775 μ m for 300mm wafers results are calculated from the technology specification documents and test results and are expressed in ppm (mg/kg) using actual densities or density estimates.

These calculations are meant to be conservative and are an attempt to represent maximums for the 200mm and 300mm wafer built at GlobalFoundries Fabs worldwide.

COMPLIANCE INFORMATION

Product meets RoHS specifications:

Concentration of Pb/Cr6+/Hg/PBB/ PBDE <1000 ppm and Cd <100 ppm concentration of Phthalates DEHP, BBP, DBP and DIBP <1000 ppm

Declaration of Non-Presence of SVHC in Finished Die Patterned Wafers according to Article 33 of REACH (REGULATION (EC) No 1907/2006):

Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH) entered into force on 1st June 2007. REACH establishes a candidate list for Substances of Very High Concern (SVHC).

Product does not contain substances classified as Substances of Very High Concern (SVHC) above the threshold of 0.1% w/w according to the SVHC candidate list in its edition of June 25th, 2025 (https://echa.europa.eu/en/candidate-list-table).

REACH ANNEX XIV:

GF finished die patterned wafers manufactured by GF entities in Singapore; Dresden, Germany; Malta, NY; and Burlington, VT are in conformance with the requirements of EU REACH Regulation (EC) No 1272/2008 ANNEX XIV (see: Authorisation List - ECHA (europa.eu).

The manufacturing operations in Dresden, Germany, GF's only fabrication plant located within the legal scope of the EU, comply with REACH ANNEX XIV.

REACH ANNEX XVII:

GF finished die patterned wafers manufactured by GF entities in Singapore; Dresden, Germany; Malta, NY; and Burlington, VT are in conformance with the restrictions of EU REACH Regulation ((EC) No 1272/2008 ANNEX XVII (see: https://echa.europa.eu/substances-restricted-under-reach)).

GF's manufacturing process of finished die patterned wafers in Dresden, Germany, which is GF's only fabrication plant that is in the legal scope of the EU, complies with REACH Regulation ((EC) No 1272/2008), including EU REACH ANNEX XVII (see: https://echa.europa.eu/authorisation-list).

Persistent Organic Pollutants (POPs) European Regulation No. 2019/1021:

The European Regulation No. 2019/1021 concerning the Persistent Organic Pollutants (POPs) is the EU's Regulation to implement the provisions of the Stockholm Convention on Persistent Organic Pollutants in the European Union. Substances that are in the scope of the regulation can be viewed at: https://echa.europa.eu/list-of-substances-subject-to-pops-regulation.

GF's finished die patterned wafers manufactured by GlobalFoundries entities in Singapore; Dresden, Germany; Malta, NY (U.S.A.); and Burlington, VT (U.S.A.), do not contain substances classified as

Persistent Organic Pollutants (POPs)) as per the conditions specified in Annex I of the EU Regulation on POPs Annex I (No. 2019/1021).

TSCA PBT:

On January 6, 2021, the United States Environmental Protection Agency ("EPA") issued five final rules aimed to reduce exposures to certain chemicals that are persistent, bioaccumulative and toxic (PBT). The rules were issued under the United States Toxic Substances Control Act (TSCA), as amended by the Frank R. Lautenberg Chemical Safety for the 21st Century Act. According to these final rules, there are a variety of prohibitions on the manufacture (including import), processing, and distribution in commerce of these substances, including within products and articles.

PBT chemicals listed in Table 1 below are not used in GF's manufacturing processes and are not intentionally included in the finished patterned wafers manufactured by GF Fabs.

Table 1 – PBT Chemicals in scope for the final TSCA rules

Table 1 1 B1 ellethicals in scope for the final recontrates			
Decabromodiphenyl ether (DecaBDE)	1163-19-5		
Phenol, isopropylated phosphate (3:1) (PIP (3:1))	68937-41-7		
2,4,6 – Tris(tert-butyl) phenol (2,4,6-TTBP)	732-26-3		
Hexachlorobutadiene (HCBD)	87-68-3		
Pentachlorothiophenol (PCTP)	133-49-3		

Halogens:

Product meets halogen content specifications as follows:

- Bromine is less than 900 ppm by weight.
- Chlorine is less than 900 ppm by weight.
- Bromine + Chlorine is less than 1500 ppm by weight.

Conflict Minerals:

In the complex, multi-step silicon wafer manufacturing process, tantalum, tungsten—and in some cases, cobalt or gold—are added to achieve the desired functionalities of integrated circuits. We routinely provide due diligence information such as Conflict Minerals Reporting Templates (CMRTs) and Extended Minerals Reporting Templates (EMRTs) to support our customers' reporting needs.

GlobalFoundries Reserves the right to change this document without notice at any time.